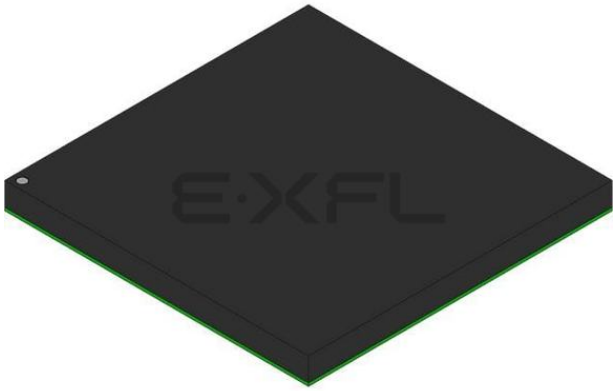


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3840
Number of Logic Elements/Cells	38400
Total RAM Bits	655360
Number of I/O	540
Number of Gates	3000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	724-BBGA, FCBGA
Supplier Device Package	724-BGA (35x35)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=ep2a40b724i8

General Description

APEX II devices integrate high-speed differential I/O support using the True-LVDS interface. The dedicated serializer, deserializer, and CDS circuitry in the True-LVDS interface support the LVDS, LVPECL, HyperTransport, and PCML I/O standards. Flexible-LVDS pins located in regular user I/O banks offer additional differential support, increasing the total device bandwidth. This circuitry, together with enhanced IOEs and support for numerous I/O standards, allows APEX II devices to meet high-speed interface requirements.

APEX II devices also include other high-performance features such as bidirectional dual-port RAM, CAM, general-purpose PLLs, and numerous global clocks.

Configuration

The logic, circuitry, and interconnects in the APEX II architecture are configured with CMOS SRAM elements. APEX II devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different ASIC designs; APEX II devices can be configured on the board for the specific functionality required.

APEX II devices are configured at system power-up with data either stored in an Altera configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable configuration devices, which configure APEX II devices via a serial data stream. The enhanced configuration devices can configure any APEX II device in under 100 ms. Moreover, APEX II devices contain an optimized interface that permits microprocessors to configure APEX II devices serially or in parallel, synchronously or asynchronously. This interface also enables microprocessors to treat APEX II devices as memory and to configure the device by writing to a virtual memory location, simplifying reconfiguration.

APEX II devices also support a new byte-wide, synchronous configuration scheme at speeds of up to 66 MHz using EPC16 configuration devices or a microprocessor. This parallel configuration reduces configuration time by using eight data lines to send configuration data versus one data line in serial configuration.

APEX II devices support multi-voltage configuration; device configuration can be performed at 3.3 V and 2.5 V or 1.8 V.

After an APEX II device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

Software

APEX II devices are supported by the Altera Quartus II development system: a single, integrated package that offers hardware description language (HDL) and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software includes the LogicLock incremental design feature. The LogicLock feature allows the designer to make pin and timing assignments, verify functionality and performance, and then set constraints to lock down the placement and performance of a specific block of logic using LogicLock constraints. Constraints set by the LogicLock function guarantee repeatable placement when implementing a block of logic in a current project or exporting the block to another project. The constraints set by the LogicLock feature can lock down logic to a fixed location in the device. The LogicLock feature can also lock the logic down to a floating location, and the Quartus II software determines the best relative placement of the block to meet design requirements. Adding additional logic to a project will not affect the performance of blocks locked down with LogicLock constraints.

The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can open the Quartus II software from within third-party design tools. The Quartus II software also contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX II devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX II architecture.

Functional Description

APEX II devices incorporate LUT-based logic, product-term-based logic, memory, and high-speed I/O standards into one device. Signal interconnections within APEX II devices (as well as to and from device pins) are provided by the FastTrack interconnect—a series of fast, continuous row and column channels that run the entire length and width of the device.

A column line can be directly driven by the LEs, IOEs, or ESBs in that column. Row IOEs can drive a column line on a device's left or right edge. The column line is used to route signals from one row to another. A column line can drive a row line; it can also drive the MegaLAB interconnect directly, allowing faster connections between rows.

Figure 10 shows how the FastTrack interconnect uses the local interconnect to drive LEs within MegaLAB structures.

Figure 10. FastTrack Connection to Local Interconnect

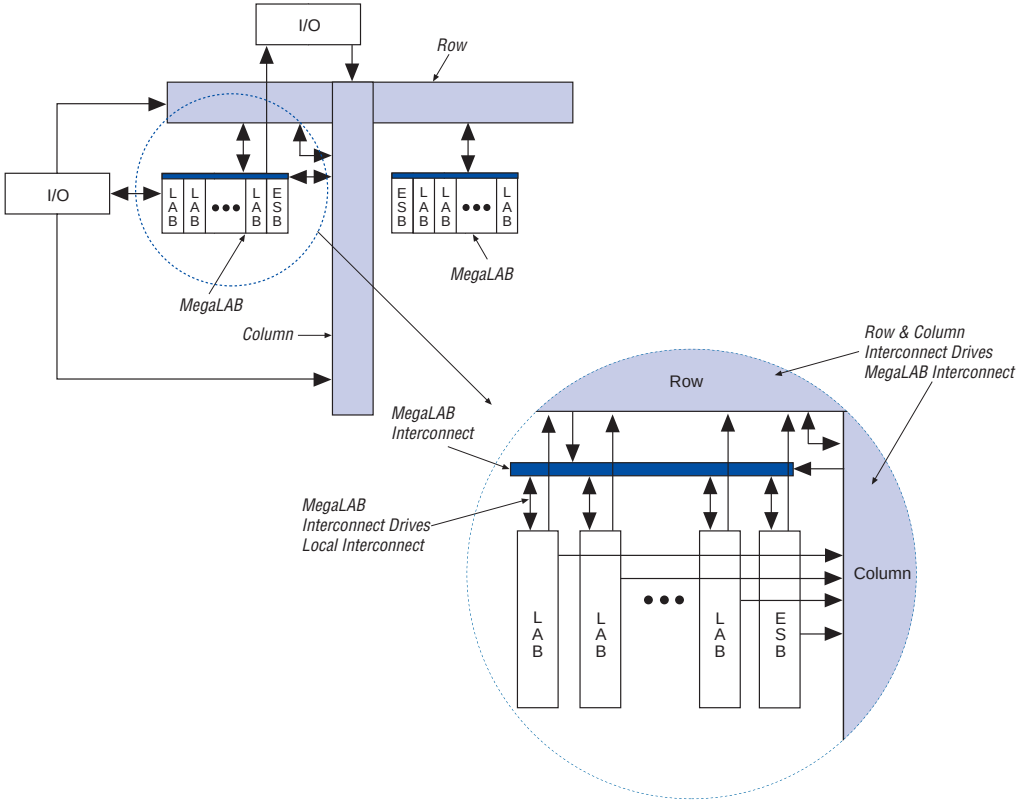


Figure 11 shows the intersection of a row and column interconnect and how these forms of interconnects and LEs drive each other.

Figure 12. APEX II FastRow Interconnect

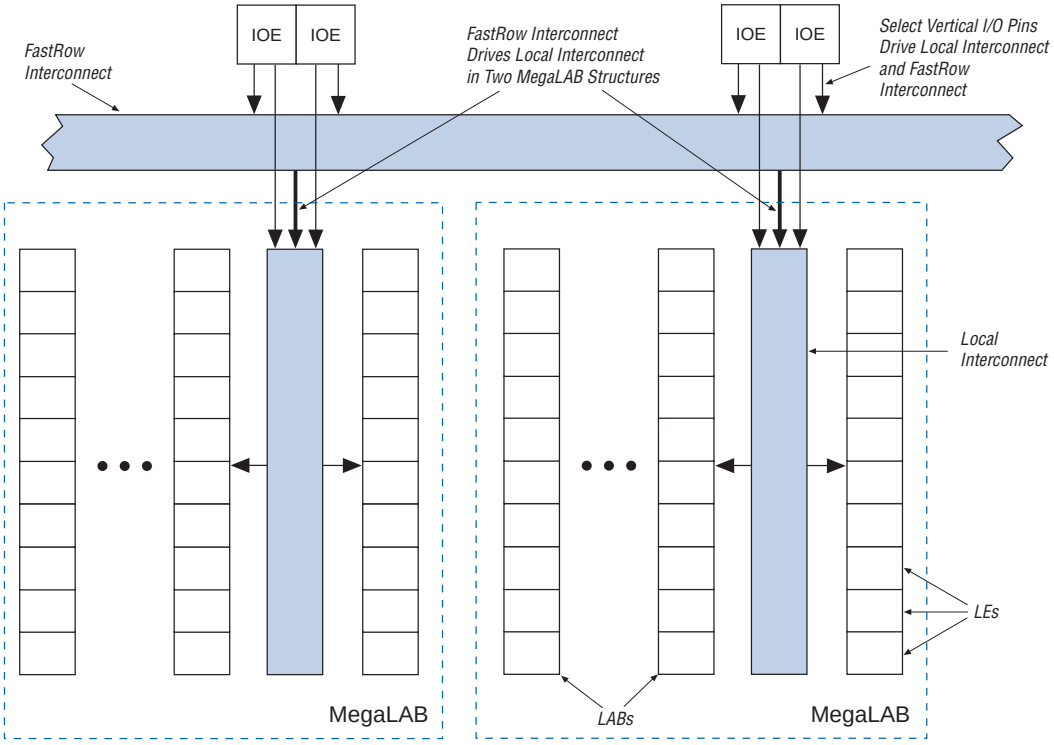


Table 5 summarizes how elements of the APEX II architecture drive each other.

Table 5. APEX II Routing Scheme

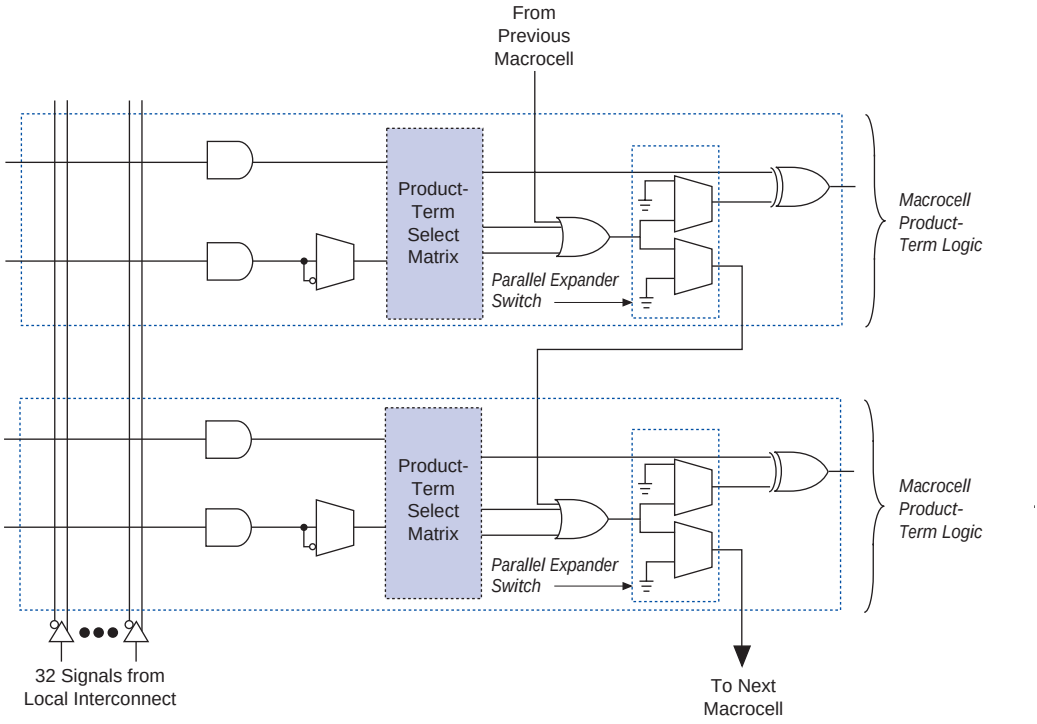
Source	Destination								
	Row I/O Pin	Column I/O Pin	LE	ESB	Local Interconnect	MegaLAB Interconnect	Row FastTrack Interconnect	Column FastTrack Interconnect	FastRow Interconnect
Row I/O pin					✓	✓	✓	✓	
Column I/O pin								✓	✓
LE					✓	✓	✓	✓	
ESB					✓	✓	✓	✓	
Local interconnect	✓	✓	✓	✓					
MegaLAB interconnect					✓				
Row FastTrack interconnect						✓		✓	
Column FastTrack interconnect						✓	✓		
FastRow interconnect					✓				

Product-Term Logic

The product-term portion of the MultiCore architecture is implemented with the ESB. The ESB can be configured to act as a block of macrocells on an ESB-by-ESB basis. 32 inputs from the adjacent local interconnect feed each ESB; therefore, the either MegaLAB or the adjacent LAB can drive the ESB. Also, nine ESB macrocells feed back into the ESB through the local interconnect for higher performance. Dedicated clock pins, global signals, and additional inputs from the local interconnect drive the ESB control signals.

In product-term mode, each ESB contains 16 macrocells. Each macrocell consists of two product terms and a programmable register. Figure 13 shows the ESB in product-term mode.

Figure 16. APEX II Parallel Expanders

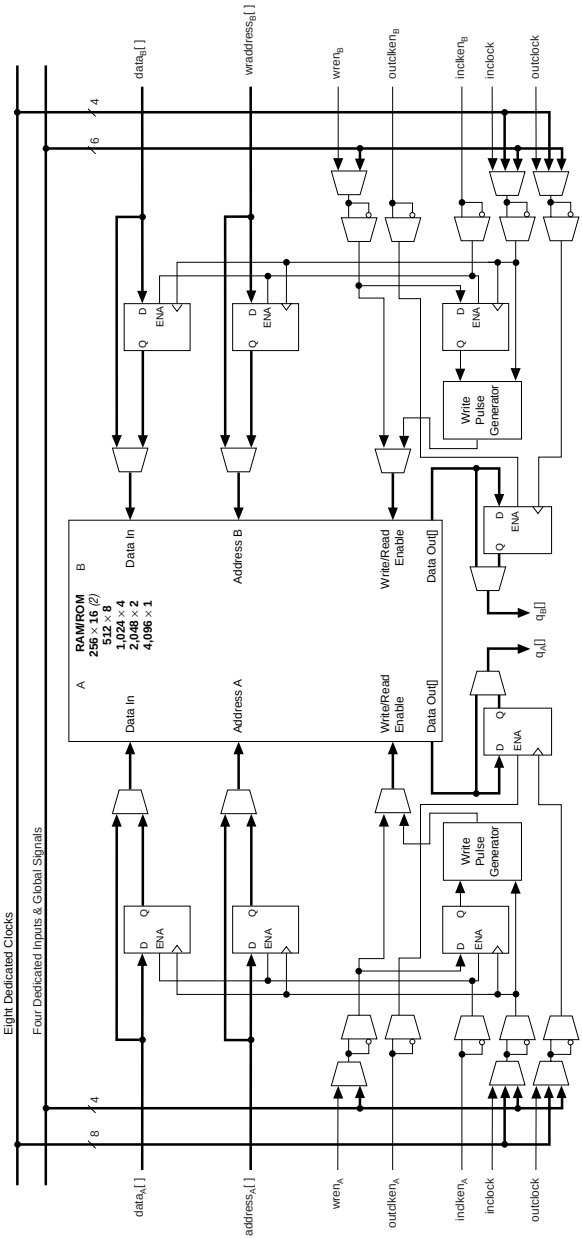


Embedded System Block

The ESB can implement various types of memory blocks, including Dual-Port+ RAM (bidirectional dual-port RAM), dual- and single-port RAM, ROM, FIFO, and CAM blocks.

The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a bidirectional, dual-port mode, which supports any combination of two port operations: two reads, two writes, or one read and one write at two different clock frequencies. Figure 17 shows the ESB block diagram.

Figure 19. ESB in Input/Output Clock Mode *Note (1)*



Notes to Figure 19:

(1) All registers can be cleared asynchronously by ESB local interconnect signals, global signals, or the chip-wide reset.

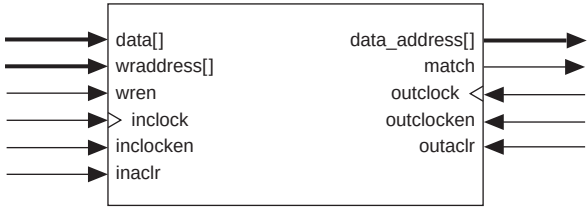
(2) This configuration is not supported for bidirectional dual-port configuration.

Content-Addressable Memory

APEX II devices can implement CAM in ESBs. CAM can be thought of as the inverse of RAM. RAM stores data in a specific location; when the system submits an address, the RAM block provides the data. Conversely, when the system submits data to CAM, the CAM block provides the address where the data is found. For example, if the data FA12 is stored in address 14, the CAM outputs 14 when FA12 is driven into it.

CAM is used for high-speed search operations. When searching for data within a RAM block, the search is performed serially. Thus, finding a particular data word can take many cycles. CAM searches all addresses in parallel and outputs the address storing a particular word. When a match is found, a match flag is set high. CAM is ideally suited for applications such as Ethernet address lookup, data compression, pattern recognition, cache tags, fast routing table lookup, and high-bandwidth address filtering. Figure 21 shows the CAM block diagram.

Figure 21. CAM Block Diagram



The APEX II on-chip CAM provides faster system performance than traditional discrete CAM. Integrating CAM and logic into the APEX II device eliminates off-chip and on-chip delays, improving system performance.

When in CAM mode, the ESB implements a 32-word, 32-bit CAM. Wider or deeper CAM, such as a 32-word, 64-bit or 128-word, 32-bit block, can be implemented by combining multiple CAM blocks with some ancillary logic implemented in LEs. The Quartus II software automatically combines ESBs and LEs to create larger CAM blocks.

CAM supports writing “don’t care” bits into words of the memory. The don’t-care bit can be used as a mask for CAM comparisons; any bit set to don’t-care has no effect on matches.

If the same data is written into multiple locations in the memory, a CAM block can be used in multiple-match or fast multiple-match modes. The ESB outputs the matched data's locations as an encoded or unencoded address. In multiple-match mode, it takes two clock cycles to write into a CAM block. For reading, there are 16 outputs from each ESB at each clock cycle. Therefore, it takes two clock cycles to represent the 32 words from a single ESB port. In this mode, encoded and unencoded outputs are available. To implement the encoded version, the Quartus II software adds a priority encoder with LEs. Fast multiple-match is identical to the multiple match mode, however, it only takes one clock cycle to read from a CAM block and generate valid outputs. To do this, the entire ESB is used to represent 16 outputs. In fast multiple-match mode, the ESB can implement a maximum CAM block size of 16 words.

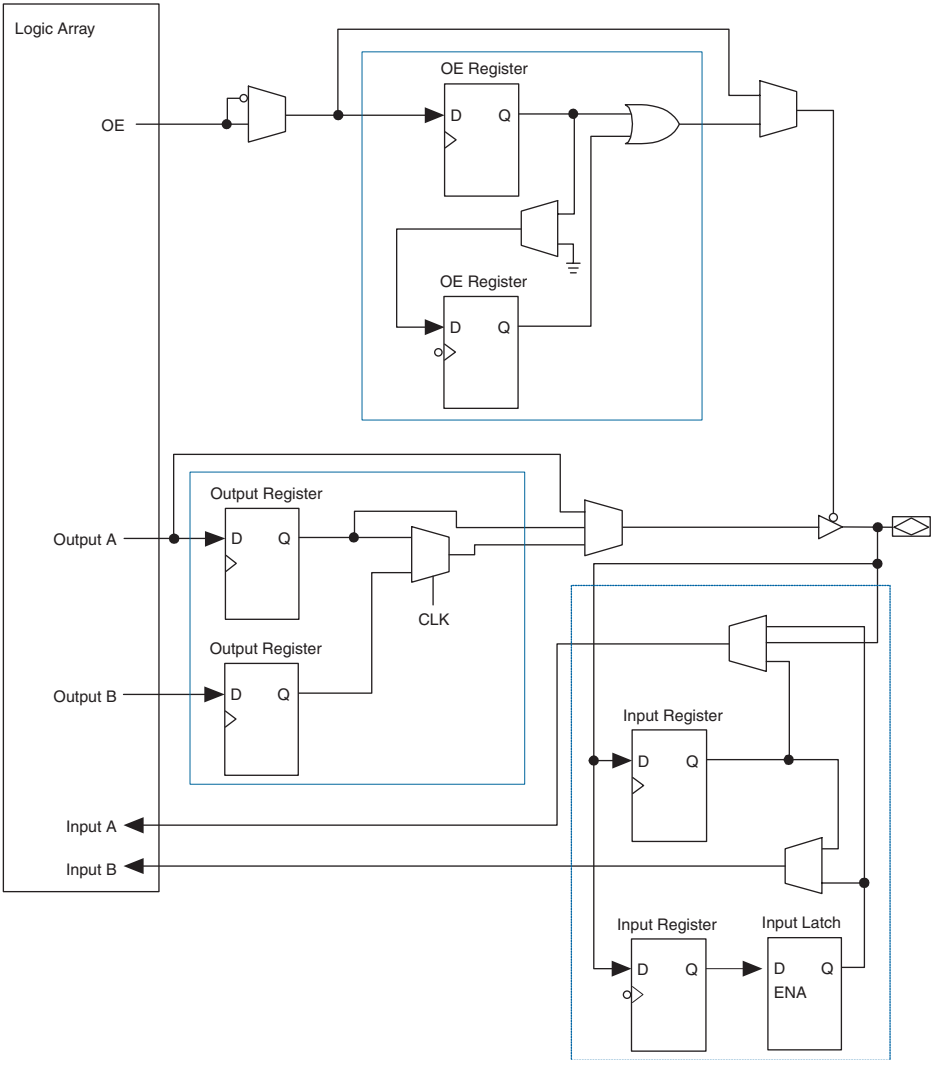
A CAM block can be pre-loaded with data during configuration, or it can be written during system operation. In most cases, two clock cycles are required to write each word into CAM. When don't-care bits are used, a third clock cycle is required.

For more information on CAM, see *Application Note 119 (Implementing High-Speed Search Applications with APEX CAM)*.

Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnects can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and synchronous clear signals. Figure 24 shows the ESB control signal generation logic.

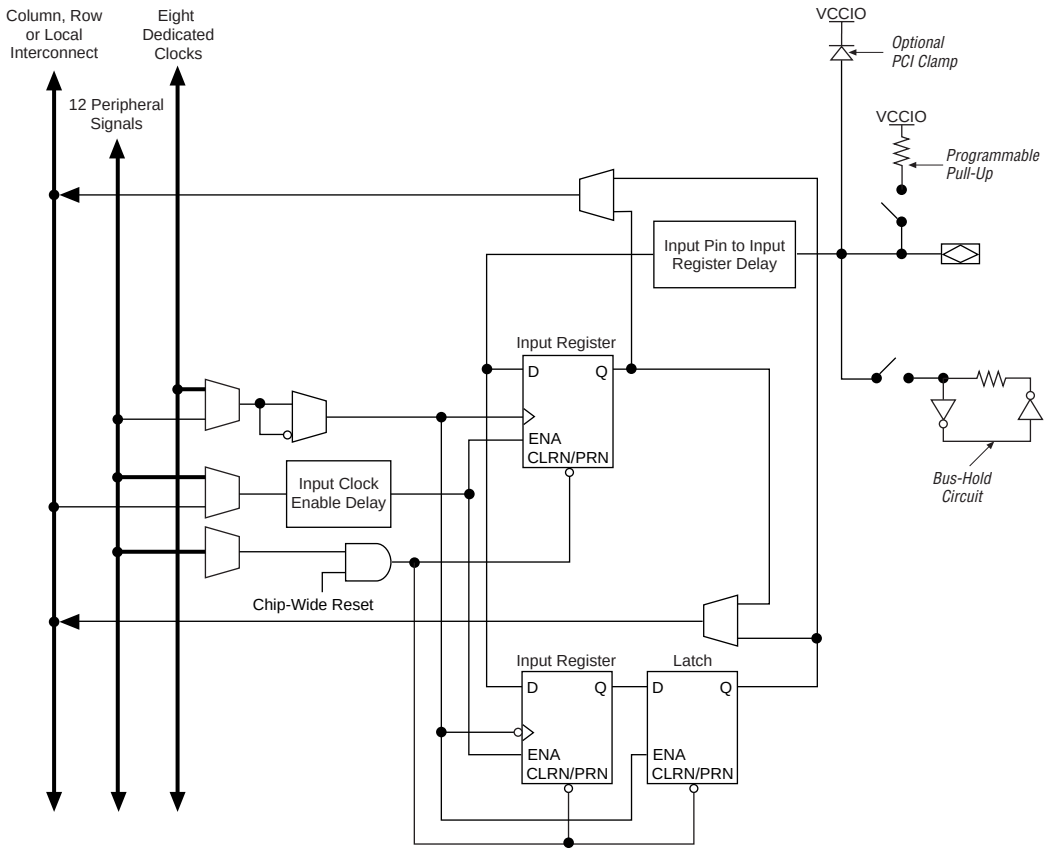
Figure 25. APEX II IOE Structure



The IOEs are located around the periphery of the APEX II device. Each IOE drives a row, column, MegaLAB, or local interconnect when used as an input or bidirectional pin. A row IOE can drive a local, MegaLAB, row, and column interconnect; a column IOE can drive the FastTrack or column interconnect. Figure 26 shows how a row IOE connects to the interconnect.

When using the IOE for DDR inputs, the two input registers are used to clock double rate input data on alternating edges. An input latch is also used within the IOE for DDR input acquisition. The latch holds the data that is present during the clock high times. This allows both bits of data to be synchronous to the same clock edge (either rising or falling). Figure 29 shows an IOE configured for DDR input.

Figure 29. APEX II IOE in DDR Input I/O Configuration



When using the IOE for DDR outputs, the two output registers are configured to clock two data paths from LEs on rising clock edges. These register outputs are multiplexed by the clock to drive the output pin at a ×2 rate. One output register clocks the first bit out on the clock high time, while the other output register clocks the second bit out on the clock low time. Figure 30 shows the IOE configured for DDR output.

Table 10 describes the I/O standards supported by APEX II devices.

Table 10. APEX II Supported I/O Standards

I/O Standard	Type	Input Reference Voltage (V_{REF}) (V)	Output Supply Voltage (V_{CCIO}) (V)	Board Termination Voltage (V_{TT}) (V)
LVTTL	Single-ended	N/A	3.3	N/A
LVCMOS	Single-ended	N/A	3.3	N/A
2.5 V	Single-ended	N/A	2.5	N/A
1.8 V	Single-ended	N/A	1.8	N/A
1.5 V	Single-ended	N/A	1.5	N/A
3.3-V PCI	Single-ended	N/A	3.3	N/A
3.3-V PCI-X	Single-ended	N/A	3.3	N/A
LVDS	Differential	N/A	3.3	N/A
LVPECL	Differential	N/A	3.3	N/A
PCML	Differential	N/A	3.3	N/A
HyperTransport	Differential	N/A	2.5	N/A
Differential HSTL *(1)*	Differential	N/A	1.5	N/A
GTL+	Voltage referenced	1.0	N/A	1.5
HSTL class I and II	Voltage referenced	0.75	1.5	0.75
SSTL-2 class I and II	Voltage referenced	1.25	2.5	1.25
SSTL-3 class I and II	Voltage referenced	1.5	3.3	1.5
AGP (1× and 2×)	Voltage referenced	1.32	3.3	N/A
CTT	Voltage referenced	1.5	3.3	1.5

Note to Table 10:

(1) Differential HSTL is only supported on the eight dedicated global clock pins and four dedicated high-speed PLL clock pins.

For more information on I/O standards supported by APEX II devices, see *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

APEX II devices contain eight I/O banks, as shown in Figure 31. Two blocks within the right I/O banks contain circuitry to support high-speed True-LVDS, LVPECL, PCML, and HyperTransport inputs, and another two blocks within the left I/O banks support high-speed True-LVDS, LVPECL, PCML, and HyperTransport outputs. All other standards are supported by all I/O banks.

Tables 20 through 41 provide information on absolute maximum ratings, recommended operating conditions, and DC operating conditions for 1.5-V APEX II devices.

Table 20. APEX II Device Absolute Maximum Ratings *Notes (1), (2)*

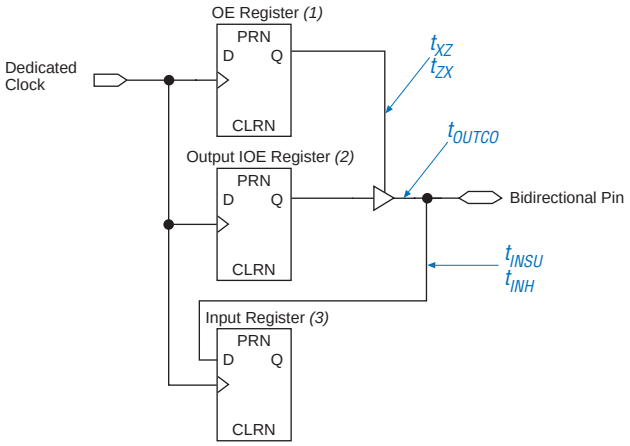
Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCINT}	Supply voltage	With respect to ground *(3)*	–0.5	2.4	V
V_{CCIO}			–0.5	4.6	V
V_I	DC input voltage		–0.5	4.6	V
I_{OUT}	DC output current, per pin		–25	25	mA
T_{STG}	Storage temperature	No bias	–65	150	° C
T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	BGA packages under bias		135	° C

Table 21. APEX II Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	*(4)*	1.425	1.575	V
V_{CCIO}	Supply voltage for output buffers, 3.3-V operation	*(4)*, *(5)*	3.00 (3.135)	3.60 (3.465)	V
	Supply voltage for output buffers, 2.5-V operation	*(4)*	2.375	2.625	V
	Supply voltage for output buffers, 1.8-V operation	*(4)*	1.71	1.89	V
	Supply voltage for output buffers, 1.5-V operation	*(4)*	1.4	1.6	V
V_I	Input voltage	*(3)*, *(6)*	–0.5	4.1	V
V_O	Output voltage		0	V_{CCIO}	V
T_J	Operating junction temperature	For commercial use	0	85	° C
		For industrial use	–40	100	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Figure 42 shows the timing model for bi-directional, input, and output IOE timing.

Figure 42. Synchronous External TIming Model



Notes to Figure 42:

(1) The output enable register is in the IOE and is controlled by the "Fast Output Enable Register = ON" option in the Quartus II software.

(2) The output register is in the IOE and is controlled by the "Fast Output Register = ON" option in the Quartus II software.

(3) The input register is in the IOE and is controlled by the "Fast Input Register = ON" option in the Quartus II software.

Tables 47 through 50 show APEX II LE, ESB, and routing delays and minimum pulse-width timing parameters for the f_{MAX} timing model.

Table 47. APEX II f_{MAX} LE Timing Parameters

Symbol	Parameter
t_{SU}	LE register setup time before clock
t_{H}	LE register hold time before clock
t_{CO}	LE register clock-to-output delay
t_{LUT}	LUT delay for data-in to data-out

Figure 43. Dual-Port RAM Timing Microparameter Waveform

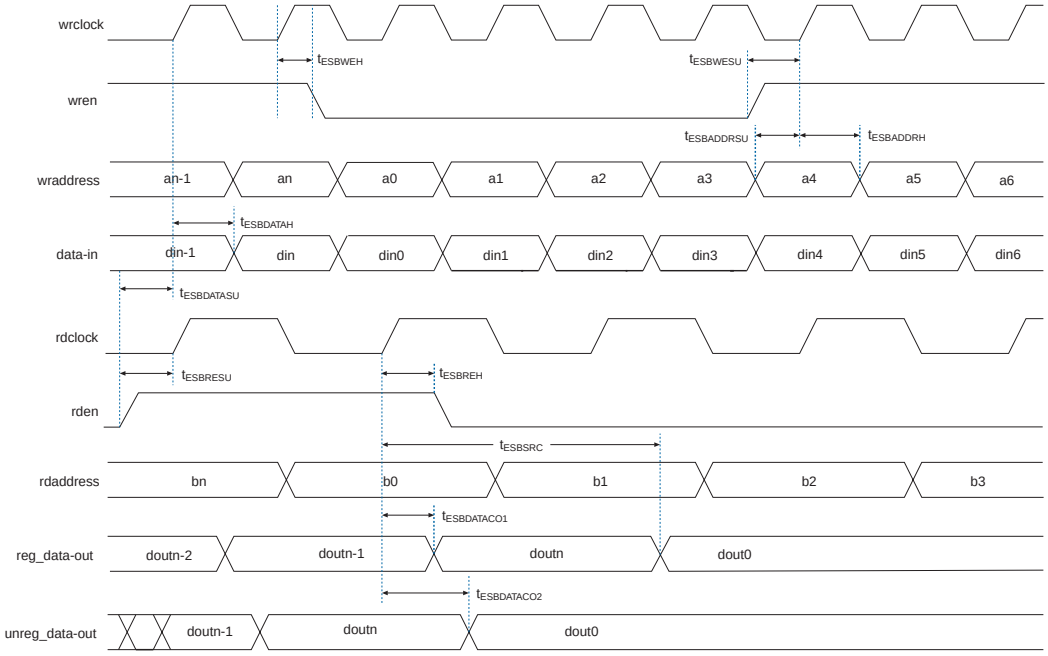


Table 49. APEX II f_{MAX} Routing Delays	
Symbol	**Parameter**
t_{F1-4}	Fan-out delay estimate using local interconnect; use to estimate routing delay for a signal with fan-out of 1 to 4
t_{F5-20}	Fan-out delay estimate using MegaLab interconnect; use to estimate routing delay for a signal with fan-out of 5 to 20
t_{F20+}	Fan-out delay estimate using FastTrack interconnect; use to estimate routing delay for a signal with fan-out greater than 20

Tables 52 through 67 show the APEX II device f_{MAX} and functional timing parameters.

Table 52. EP2A15 f_{MAX} LE Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.25		0.29		0.33		ns
t_{H}	0.25		0.29		0.33		ns
t_{CO}		0.18		0.20		0.23	ns
t_{LUT}		0.53		0.61		0.70	ns

Table 53. EP2A15 f_{MAX} ESB Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.28		1.47		1.69	ns
t_{ESBSRC}		2.49		2.86		3.29	ns
t_{ESBAWC}		2.20		2.53		2.91	ns
t_{ESBSWC}		3.02		3.47		3.99	ns
$t_{ESBWASU}$	– 0.55		– 0.64		– 0.73		ns
t_{ESBWAH}	0.15		0.18		0.20		ns
$t_{ESBWDSU}$	0.37		0.43		0.49		ns
t_{ESBWDH}	0.16		0.18		0.21		ns
$t_{ESBRASU}$	0.84		0.96		1.11		ns
t_{ESBRAH}	0.00		0.00		0.00		ns
$t_{ESBWESU}$	0.14		0.16		0.19		ns
$t_{ESBDATASU}$	– 0.02		– 0.03		– 0.03		ns
$t_{ESBWADDRSU}$	– 0.40		– 0.46		– 0.53		ns
$t_{ESBRADDRSU}$	– 0.38		– 0.44		– 0.51		ns
$t_{ESBDATACO1}$		1.30		1.50		1.72	ns
$t_{ESBDATACO2}$		1.84		2.12		2.44	ns
t_{ESBDD}		2.42		2.78		3.19	ns
t_{PD}		1.69		1.94		2.23	ns
$t_{PTERMSU}$	1.10		1.26		1.45		ns
$t_{PTERMCO}$		0.82		0.94		1.08	ns

Table 57. EP2A25 f_{MAX} ESB Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.28		1.47		1.69	ns
t_{ESBSRC}		2.49		2.86		3.29	ns
t_{ESBAWC}		2.20		2.53		2.91	ns
t_{ESBSWC}		3.02		3.47		3.99	ns
$t_{ESBWASU}$	0.07		0.07		0.09		ns
t_{ESBWAH}	0.15		0.18		0.20		ns
$t_{ESBWDSU}$	0.37		0.43		0.49		ns
t_{ESBWDH}	0.16		0.18		0.21		ns
$t_{ESBRASU}$	0.84		0.96		1.11		ns
t_{ESBRAH}	0.00		0.00		0.00		ns
$t_{ESBWESU}$	0.14		0.16		0.19		ns
$t_{ESBDATASU}$	– 0.02		– 0.03		– 0.03		ns
$t_{ESBWADDRSU}$	– 0.40		– 0.46		– 0.53		ns
$t_{ESBRADDRSU}$	– 0.38		– 0.44		– 0.51		ns
$t_{ESBDATACO1}$		1.30		1.50		1.72	ns
$t_{ESBDATACO2}$		1.84		2.12		2.44	ns
t_{ESBDD}		2.42		2.78		3.19	ns
t_{PD}		1.69		1.94		2.23	ns
$t_{PTERMSU}$	1.10		1.26		1.45		ns
$t_{PTERMCO}$		0.82		0.94		1.08	ns

Table 58. EP2A25 f_{MAX} Routing Delays

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}	0.19		0.21		0.25		ns
t_{F5-20}	0.65		0.75		0.86		ns
t_{F20+}	1.11		1.27		1.46		ns

Table 59. EP2A25 Minimum Pulse Width Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	1.00		1.50		2.12		ns
t_{CL}	1.00		1.50		2.12		ns
t_{CLRP}	0.13		0.15		0.17		ns
t_{PREP}	0.13		0.15		0.17		ns
t_{ESBCH}	1.00		1.50		2.12		ns
t_{ESBCL}	1.00		1.50		2.12		ns
t_{ESBWP}	1.12		1.28		1.48		ns
t_{ESBRP}	0.88		1.02		1.17		ns

Table 60. EP2A40 f_{MAX} LE Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.22		0.26		0.29		ns
t_{H}	0.22		0.26		0.29		ns
t_{CO}		0.16		0.18		0.21	ns
t_{LUT}		0.48		0.55		0.63	ns

Table 69. EP2A15 External Timing Parameters for Column I/O Pins

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.16		2.34		2.53		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	4.36	2.00	4.75	2.00	5.18	ns
t_{XZ}		5.57		6.24		6.97	ns
t_{ZX}		5.57		6.24		6.97	ns
$t_{INSUPLL}$	1.24		1.37		1.52		ns
t_{INHPLL}	0.00		0.00		0.00		ns
$t_{OUTCOPLL}$	0.50	2.90	0.50	3.16	0.50	3.45	ns
t_{XZPLL}		4.12		4.65		5.23	ns
t_{ZXPLL}		4.12		4.65		5.23	ns

Table 70. EP2A25 External Timing Parameters for Row I/O Pins

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.92		2.08		2.26		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	4.29	2.00	4.62	2.00	4.98	ns
t_{XZ}		5.24		5.73		6.26	ns
t_{ZX}		5.24		5.73		6.26	ns
$t_{INSUPLL}$	1.17		1.27		1.40		ns
t_{INHPLL}	0.00		0.00		0.00		ns
$t_{OUTCOPLL}$	0.50	2.61	0.50	2.83	0.50	3.07	ns
t_{XZPLL}		3.55		3.93		4.35	ns
t_{ZXPLL}		3.55		3.93		4.35	ns

Table 73. EP2A40 External Timing Parameters for Column I/O Pins

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.00		2.16		2.33		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	4.96	2.00	5.29	2.00	5.64	ns
t_{XZ}		7.04		7.59		8.19	ns
t_{ZX}		7.04		7.59		8.19	ns
$t_{INSUPLL}$	1.20		1.31		1.43		ns
t_{INHPLL}	0.00		0.00		0.00		ns
$t_{OUTCOPLL}$	0.50	2.66	0.50	2.87	0.50	3.09	ns
t_{XZPLL}		4.74		5.17		5.64	ns
t_{ZXPLL}		4.74		5.17		5.64	ns

Table 74. EP2A70 External Timing Parameters for Row I/O Pins

Symbol	-7 Speed Grade		-8 Speed Grade		-9 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.48		2.68		2.90		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	4.76	2.00	5.12	2.00	5.51	ns
t_{XZ}		5.68		6.19		6.76	ns
t_{ZX}		5.68		6.19		6.76	ns
$t_{INSUPLL}$	1.19		1.30		1.43		ns
t_{INHPLL}	0.00		0.00		0.00		ns
$t_{OUTCOPLL}$	0.50	2.52	0.50	2.74	0.50	2.98	ns
t_{XZPLL}		3.44		3.82		4.23	ns
t_{ZXPLL}		3.44		3.82		4.23	ns